

# Specification STK10025

## 10 Layers Stackup

Conductive Layer	Material Type	Thickness (mm)	Dielectric Constant	Description
	Dielectric	0,005	1	Solder Mask
L1	Conductive	0,042 (0,017+,025)		Copper foil+Plate
	Dielectric	0,100	4,3	Prepreg
L2	Conductive	0,017		Copper
	Dielectric	0,120	4,3	Core
L3	Conductive	0,017		Copper
	Dielectric	0,200	4,3	Prepreg
L4	Conductive	0,017		Copper
	Dielectric	0,152	4,3	Core
L5	Conductive	0,017		Copper
	Dielectric	0,200	4,3	Prepreg
L6	Conductive	0,017		Copper
	Dielectric	0,152	4,3	Core
L7	Conductive	0,017		Copper
	Dielectric	0,200	4,3	Prepreg
L8	Conductive	0,017		Copper
	Dielectric	0,120	4,3	Core
L9	Conductive	0,017		Copper
	Dielectric	0,100	4,3	Prepreg
L10	Conductive	0,042 (0,017+,025)		Copper foil+Plate
	Dielectric	0,005	1	Solder Mask

Total (mm)  
1,574

Total Layer  
10

Total Finished(mm)  
1,6 +/- 10%

Pre-preg type FR4 for lead-free process  
Inner type FR4 for lead-free process

